METHOD OF ATTACHING A FLEXIBLE CIRCUIT TO A SUBSTRATE

ABSTRACT

A novel method for bonding a flexible circuit (10) to a substrate (32) is provided. The method uses an adhesive that is curable upon exposure to actinic radiation of a preselected wavelength, and a flexible circuit that comprises a dielectric layer (12) made from a material that is transmissive to actinic radiation of the preselected wavelength and at least one conductive layer disposed on a surface of the dielectric layer (12). In one embodiment, the method comprises the steps of dispensing the adhesive in the channels of the substrate (32); aligning the flexible circuit (10) with the substrate (32) so that at least a portion of one opening in the conductive layer (14) of the flexible circuit (10) overlays a portion of one or more channels (36-40) in the substrate; contacting the flexible circuit (10) with the mating region of the substrate (32); and directing actinic radiation through the flexible circuit for a sufficient time to cure the adhesive and to provide the circuit board assembly.

Fig. 1

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